



Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
 [List multiple models if applicable.]

HP Compaq nc6400 Notebook PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Mother board, PCMCIA board	2
Batteries	All types including standard alkaline and lithium coin or button style batteries 6 cell battery and RTC battery	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries LCD lamp	1
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 screw driver	T8
Description #2 screw driver	philip #0 #1
Description #3 screw driver	philip 4.0 mm
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove primary battery module
2. Remove HDD module (contains PCA)
3. Remove expansion memory module (contains PCA)
4. Remove minicard module (contains PCA)
5. Remove ODD assembly (contains PCA)
6. Remove Bluetooth module (contains PCA)
7. Remove Keyboard
8. Remove strip cover
9. Remove LCD cable and antenna
10. Divide LCD assembly from base assembly
11. Remove FAN assembly from base assembly
12. Remove thermal assembly from base assembly
13. Divide logic-up assembly(with RTC coin cell Battery) from base assembly
14. Remove RTC coin cell battery
15. Remove PCMCIA PCA
16. Remove speaker
17. Remove modem module and RJ-11 wire from logic-lower PCA
18. Divide M/B(with CPU and memory) and logic-lower PCA
19. Dismantling LCD module: tear off cover film and tape
20. Unscrew and remove PCA on the panel
21. Tear off fixing tape
22. Dismantle the panel
23. Separate sheet
24. Dismantle lamp unit and remove mercury lamp for selective treatment

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

